



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPD135N03L G	<b>Issued</b>	17. February 2022
<b>MA#</b>	MA005698423		
<b>Package</b>	PG-TO252-3-311	<b>Weight*</b>	316.47 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.562	0.18	0.18	1775	1775
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	iron	7439-89-6	0.143	0.05		453	
	non noble metal	copper	7440-50-8	143.098	45.20	45.26	452174	452763
wire	non noble metal	aluminium	7429-90-5	1.036	0.33	0.33	3272	3272
encapsulation	organic material	carbon black	1333-86-4	0.325	0.10		1027	
	plastics	epoxy resin	-	19.613	6.20		61975	
	inorganic material	silicondioxide	60676-86-0	127.750	40.37	46.67	403676	466678
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11818	11818
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	273	274
solder	non noble metal	tin	7440-31-5	0.017	0.01		55	
	noble metal	silver	7440-22-4	0.022	0.01		69	
	non noble metal	lead	7439-92-1	0.829	0.26	0.28	2619	2743
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.06	6.07	60598	60677
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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